



ON Semiconductor®

## FCH47N60F

### N-Channel SuperFET® FRFET® MOSFET

**600 V, 47 A, 73 mΩ**

#### Features

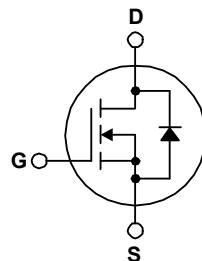
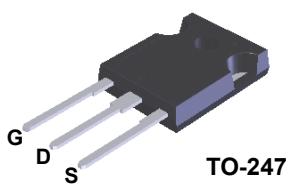
- 650 V @  $T_J = 150^\circ\text{C}$
- Typ.  $R_{DS(on)} = 58 \text{ m}\Omega$
- Ultra Low Gate Charge (Typ.  $Q_g = 210 \text{ nC}$ )
- Low Effective Output Capacitance (Typ.  $C_{oss,eff.} = 420 \text{ pF}$ )
- 100% Avalanche Tested
- RoHS Compliant

#### Applications

- Solar Inverter
- AC-DC Power Supply

#### Description

SuperFET® MOSFET is ON Semiconductor's first generation of high voltage super-junction (SJ) MOSFET family that is utilizing charge balance technology for outstanding low on-resistance and lower gate charge performance. This technology is tailored to minimize conduction loss, provide superior switching performance, dv/dt rate and higher avalanche energy. Consequently, SuperFET MOSFET is very suitable for the switching power applications such as PFC, server / telecom power, FPD TV power, ATX power and industrial power applications. Super-FET FRFET® MOSFET's optimized body diode reverse recovery performance can remove additional component and improve system reliability.



#### Absolute Maximum Ratings $T_C = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	FCH47N60F_F133	Unit
$V_{DSS}$	Drain-Source Voltage	600	V
$I_D$	Drain Current - Continuous ( $T_C = 25^\circ\text{C}$ ) - Continuous ( $T_C = 100^\circ\text{C}$ )	47 29.7	A A
$I_{DM}$	Drain Current - Pulsed	(Note 1)	A
$V_{GSS}$	Gate-Source voltage	$\pm 30$	V
$E_{AS}$	Single Pulsed Avalanche Energy	(Note 2)	mJ
$I_{AR}$	Avalanche Current	(Note 1)	A
$E_{AR}$	Repetitive Avalanche Energy	(Note 1)	mJ
$dv/dt$	Peak Diode Recovery $dv/dt$	(Note 3)	V/ns
$P_D$	Power Dissipation ( $T_C = 25^\circ\text{C}$ ) - Derate above $25^\circ\text{C}$	417 3.33	W W/ $^\circ\text{C}$
$T_J, T_{STG}$	Operating and Storage Temperature Range	-55 to +150	$^\circ\text{C}$
$T_L$	Maximum Lead Temperature for Soldering Purpose, 1/8" from Case for 5 Seconds	300	$^\circ\text{C}$

#### Thermal Characteristics

Symbol	Parameter	FCH47N60F_F133	Unit
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case, Max.	0.3	$^\circ\text{C}/\text{W}$
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient, Max.	41.7	$^\circ\text{C}/\text{W}$

## Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FCH47N60F	FCH47N60F-F133	TO-247	-	-	30

## Electrical Characteristics

$T_C = 25^\circ\text{C}$  unless otherwise noted

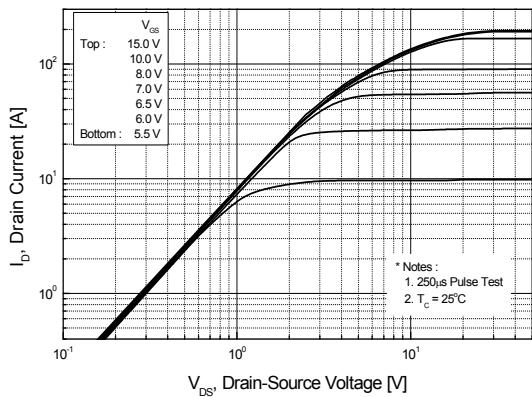
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Off Characteristics</b>						
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	$V_{GS} = 0V, I_D = 250\mu\text{A}, T_J = 25^\circ\text{C}$	600	--	--	V
		$V_{GS} = 0V, I_D = 250\mu\text{A}, T_J = 150^\circ\text{C}$	--	650	--	V
$\Delta BV_{DSS} / \Delta T_J$	Breakdown Voltage Temperature Coefficient	$I_D = 250\mu\text{A}$ , Referenced to $25^\circ\text{C}$	--	0.6	--	$^\circ\text{C}$
BV <sub>DS</sub>	Drain-Source Avalanche Breakdown Voltage	$V_{GS} = 0V, I_D = 47\text{A}$	--	700	--	V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	$V_{DS} = 600\text{V}, V_{GS} = 0\text{V}$ $V_{DS} = 480\text{V}, T_C = 125^\circ\text{C}$	--	--	10	$\mu\text{A}$
I <sub>GSSF</sub>	Gate-Body Leakage Current, Forward	$V_{GS} = 30\text{V}, V_{DS} = 0\text{V}$	--	--	100	nA
I <sub>GSSR</sub>	Gate-Body Leakage Current, Reverse	$V_{GS} = -30\text{V}, V_{DS} = 0\text{V}$	--	--	-100	nA
<b>On Characteristics</b>						
V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$	3.0	--	5.0	V
R <sub>DS(on)</sub>	Static Drain-Source On-Resistance	$V_{GS} = 10\text{V}, I_D = 23.5\text{A}$	--	0.062	0.073	$\Omega$
g <sub>FS</sub>	Forward Transconductance	$V_{DS} = 40\text{V}, I_D = 23.5\text{A}$	--	40	--	S
<b>Dynamic Characteristics</b>						
C <sub>iss</sub>	Input Capacitance	$V_{DS} = 25\text{V}, V_{GS} = 0\text{V}$ $f = 1.0\text{MHz}$	--	5900	8000	pF
C <sub>oss</sub>	Output Capacitance		--	3200	4200	pF
C <sub>rss</sub>	Reverse Transfer Capacitance		--	250	--	pF
C <sub>oss</sub>	Output Capacitance	$V_{DS} = 480\text{V}, V_{GS} = 0\text{V}, f = 1.0\text{MHz}$	--	160	--	pF
C <sub>oss eff.</sub>	Effective Output Capacitance	$V_{DS} = 0\text{V to } 400\text{V}, V_{GS} = 0\text{V}$	--	420	--	pF
<b>Switching Characteristics</b>						
t <sub>d(on)</sub>	Turn-On Delay Time	$V_{DD} = 300\text{V}, I_D = 47\text{A}$ $R_G = 25\Omega$	--	185	430	ns
t <sub>r</sub>	Turn-On Rise Time		--	210	450	ns
t <sub>d(off)</sub>	Turn-Off Delay Time		--	520	1100	ns
t <sub>f</sub>	Turn-Off Fall Time		--	75	160	ns
Q <sub>g</sub>	Total Gate Charge	$V_{DS} = 480\text{V}, I_D = 47\text{A}$ $V_{GS} = 10\text{V}$	--	210	270	nC
Q <sub>gs</sub>	Gate-Source Charge		--	38	--	nC
Q <sub>gd</sub>	Gate-Drain Charge		--	110	--	nC
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
I <sub>S</sub>	Maximum Continuous Drain-Source Diode Forward Current	--	--	47	--	A
I <sub>SM</sub>	Maximum Pulsed Drain-Source Diode Forward Current	--	--	141	--	A
V <sub>SD</sub>	Drain-Source Diode Forward Voltage	$V_{GS} = 0\text{V}, I_S = 47\text{A}$	--	--	1.4	V
t <sub>rr</sub>	Reverse Recovery Time	$V_{GS} = 0\text{V}, I_S = 47\text{A}$ $dI_F/dt = 100\text{A}/\mu\text{s}$	--	240	--	ns
Q <sub>rr</sub>	Reverse Recovery Charge		--	2.04	--	$\mu\text{C}$

### NOTES:

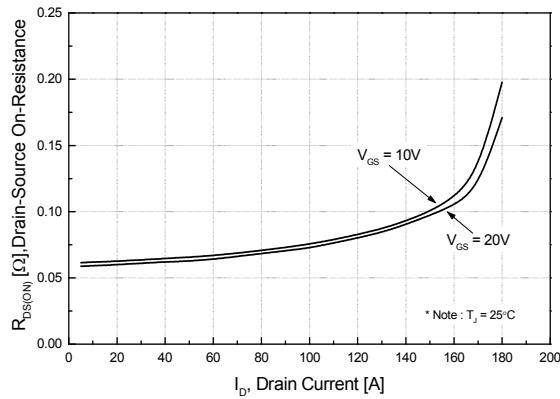
1. Repetitive Rating: Pulse width limited by maximum junction temperature
2. I<sub>AS</sub> = 18A, V<sub>DD</sub> = 50V, R<sub>G</sub> = 25Ω, Starting T<sub>J</sub> = 25°C
3. I<sub>SD</sub> ≤ 47A, di/dt ≤ 1200A/μs, V<sub>DD</sub> ≤ BV<sub>DSS</sub>, Starting T<sub>J</sub> = 25°C
4. Essentially Independent of Operating Temperature Typical Characteristics

## Typical Performance Characteristics

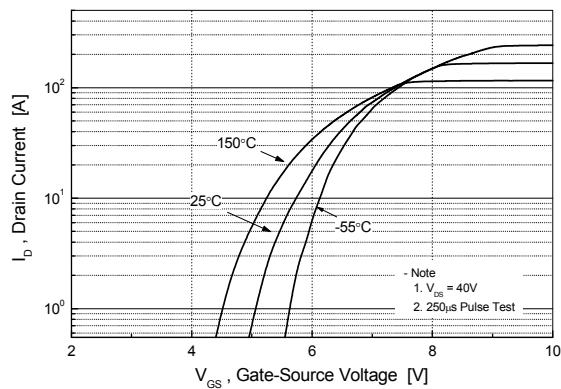
**Figure 1. On-Region Characteristics**



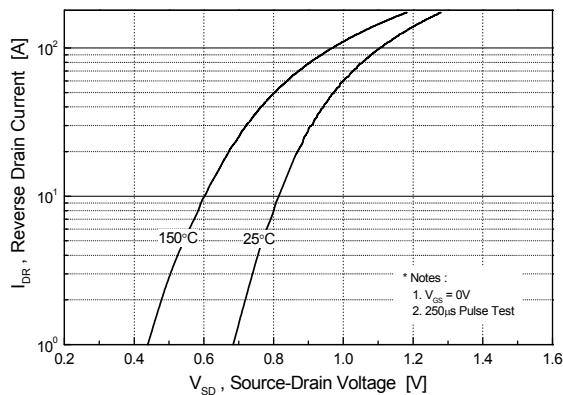
**Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage**



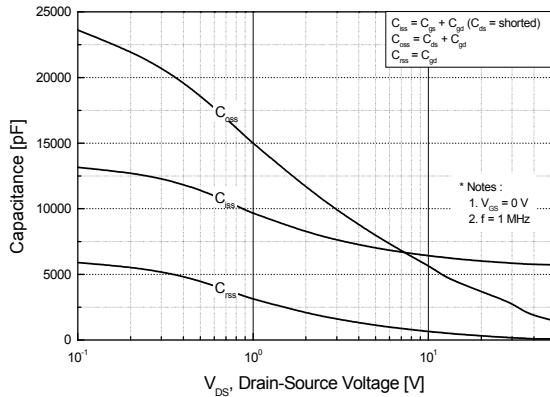
**Figure 2. Transfer Characteristics**



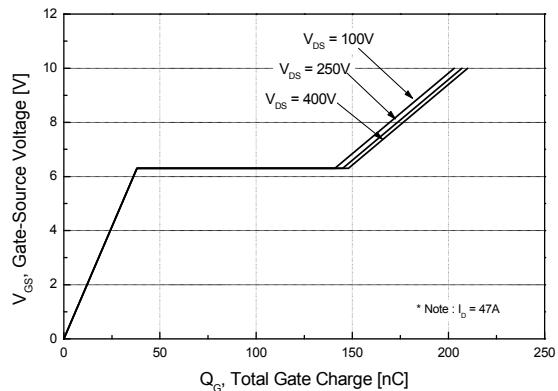
**Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature**



**Figure 5. Capacitance Characteristics**

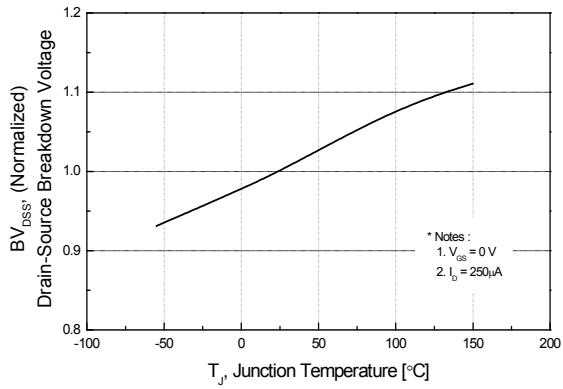


**Figure 6. Gate Charge Characteristics**

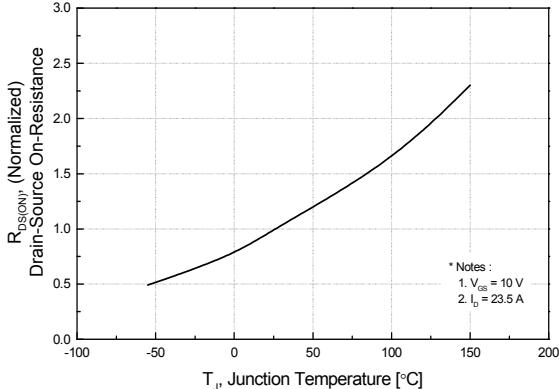


## Typical Performance Characteristics (Continued)

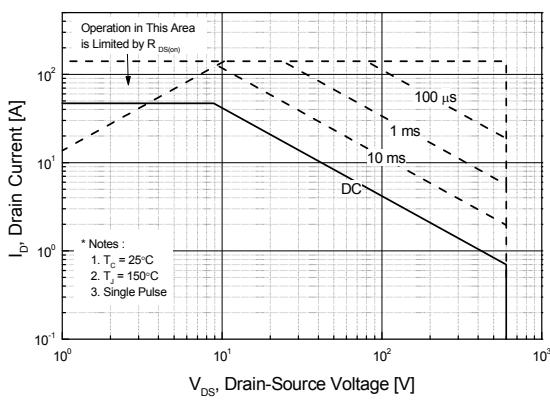
**Figure 7. Breakdown Voltage Variation vs. Temperature**



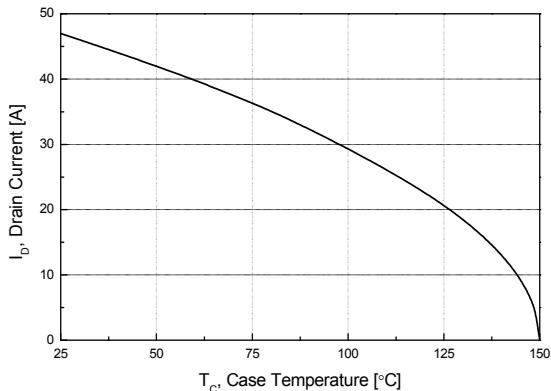
**Figure 8. On-Resistance Variation vs. Temperature**



**Figure 9. Safe Operating Area**



**Figure 10. Maximum Drain Current vs. Case Temperature**



**Figure 11. Transient Thermal Response Curve**

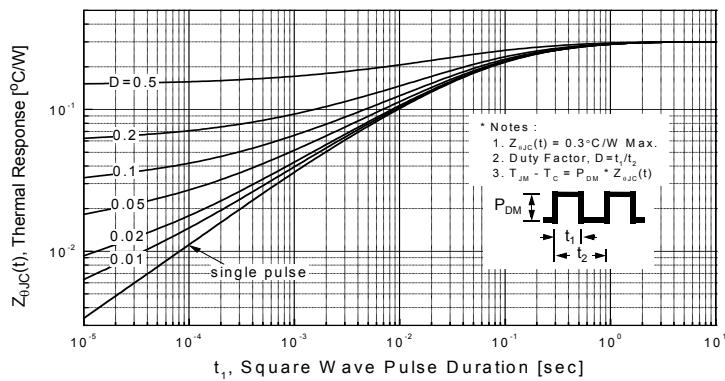


Figure 12. Gate Charge Test Circuit & Waveform

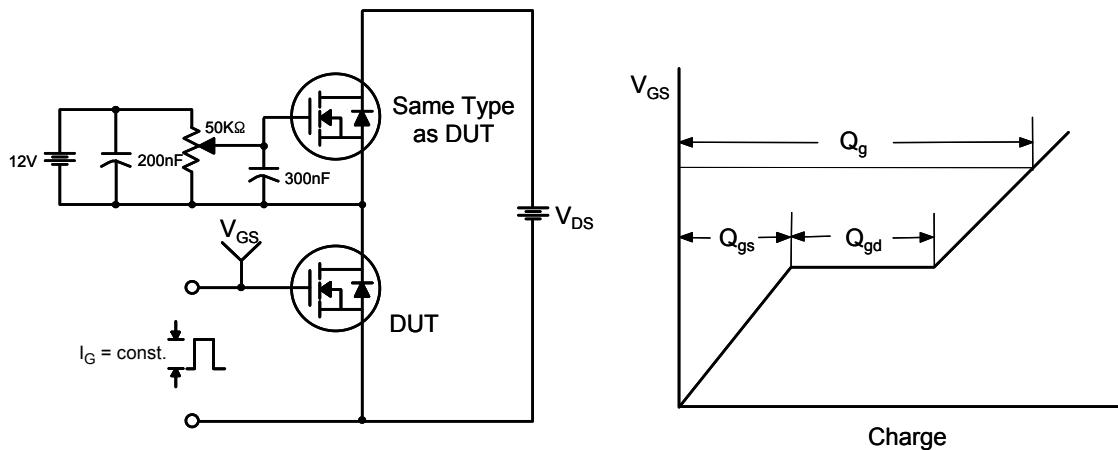


Figure 13. Resistive Switching Test Circuit & Waveforms

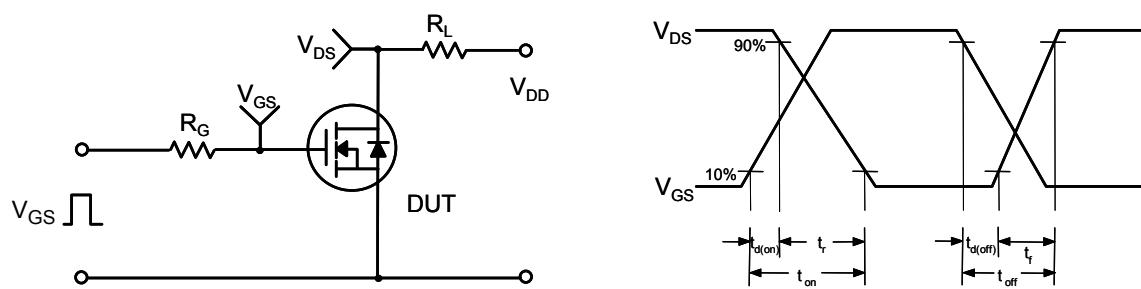


Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms

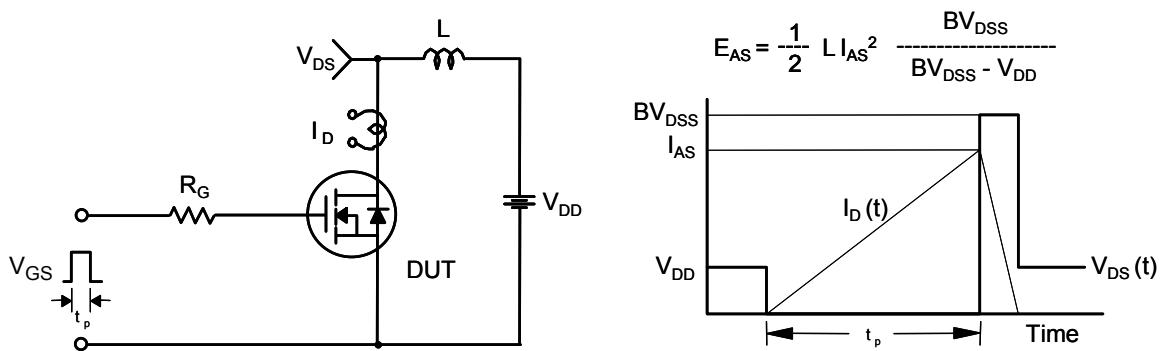
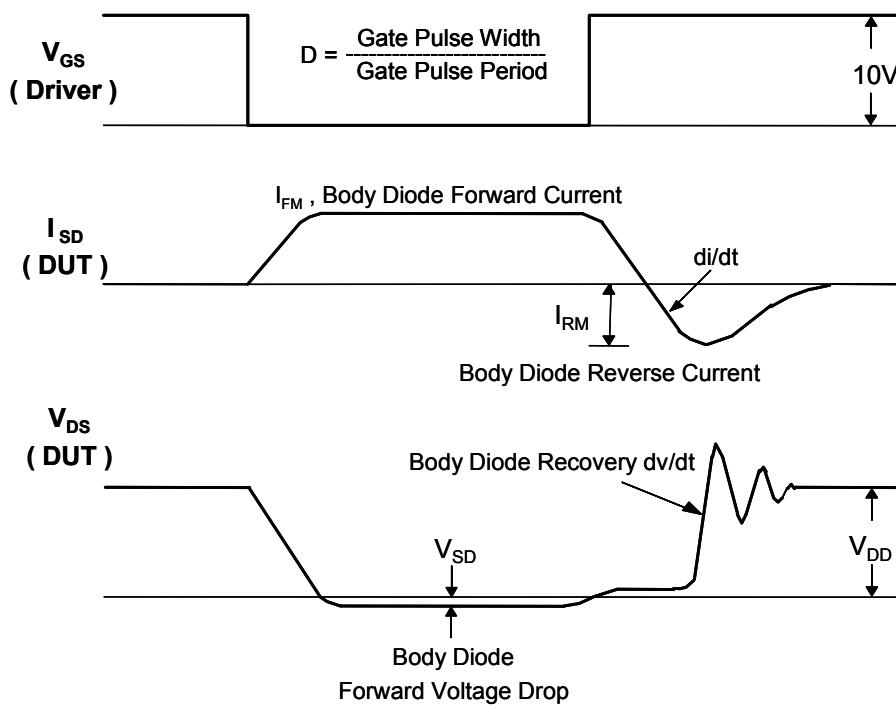
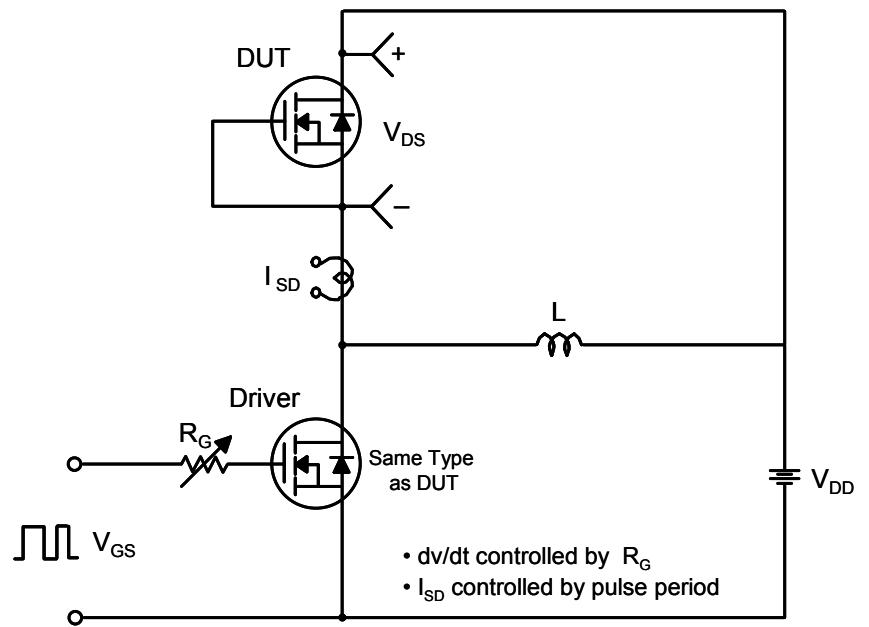
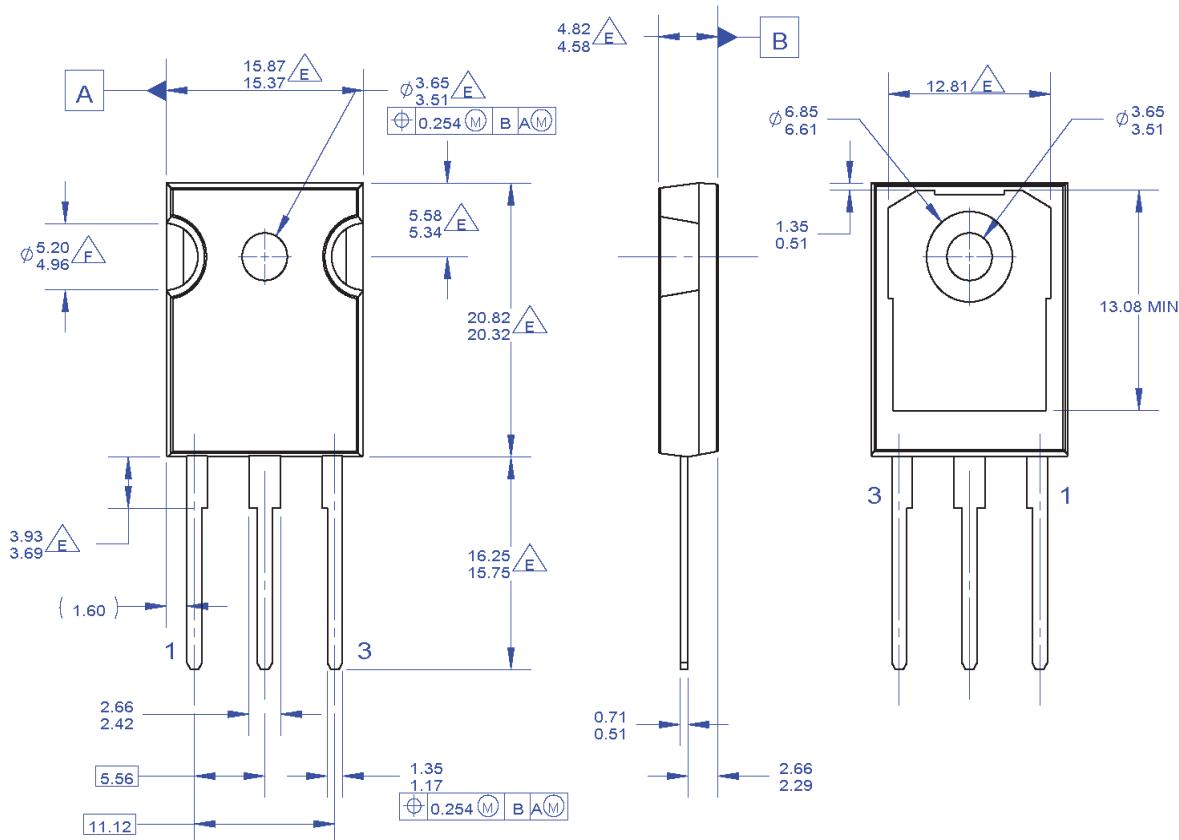


Figure 15. Peak Diode Recovery dv/dt Test Circuit & Waveforms



## Mechanical Dimensions

TO-247 3L



NOTES: UNLESS OTHERWISE SPECIFIED.

- PACKAGE REFERENCE: JEDEC TO-247, ISSUE E, VARIATION AB, DATED JUNE, 2004.
- DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
- ALL DIMENSIONS ARE IN MILLIMETERS.
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$\triangle$  DOES NOT COMPLY JEDEC STANDARD VALUE

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Figure 16. TO-247,Molded, 3 Lead, Jedec Variation AB

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Dimension in Millimeters

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